

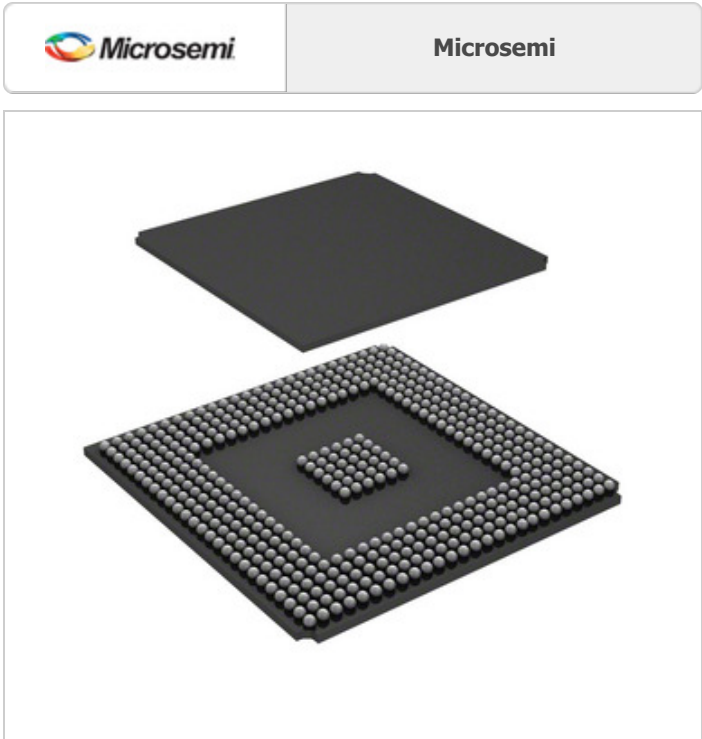


Image may be representation. See specifications for product details.

APA600-BG456

Part Number:	APA600-BG456
Manufacturer/Brand:	Microsemi
Product description	IC FPGA 356 I/O 456BGA
Datasheets:	 APA600-BG456.pdf
RoHs Status	 Contains lead / RoHS non-compliant
Ship From	Hong Kong
Shipment Way	DHL/Fedex/TNT/UPS/EMS

REQUEST FOR QUOTATION

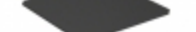
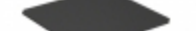
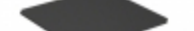
Specifications of APA600-BG456

PART NUMBER	APA600-BG456
MANUFACTURER	Microsemi
DESCRIPTION	IC FPGA 356 I/O 456BGA
LEAD FREE STATUS / ROHS STATUS	Contains lead / RoHS non-compliant
DATA SHEET	 APA600-BG456.pdf
VOLTAGE - SUPPLY	2.3 V ~ 2.7 V
TOTAL RAM BITS	129024
SUPPLIER DEVICE PACKAGE	456-PBGA (35x35)
SERIES	ProASICPLUS
PACKAGE / CASE	456-BBGA
OPERATING TEMPERATURE	0°C ~ 70°C (TA)
NUMBER OF I/O	356
NUMBER OF GATES	600000
MOUNTING TYPE	Surface Mount
MOISTURE SENSITIVITY LEVEL (MSL)	3 (168 Hours)
MANUFACTURER STANDARD LEAD TIME	10 Weeks
LEAD FREE STATUS / ROHS STATUS	Contains lead / RoHS non-compliant
BASE PART NUMBER	APA600

Related Tags

Microsemi APA600-BG456	APA600-BG456 Distributor	APA600-BG456 Supplier
APA600-BG456 Price	APA600-BG456 Pictures	APA600-BG456 Image
APA600-BG456 PDF Datasheet	APA600-BG456 Download Datasheet	APA600-BG456 Datasheet
APA600-BG456 Stock	Buy APA600-BG456	Buy Microsemi APA600-BG456
Microsemi APA600-BG456	Microsemi Supplier	Microsemi Distributor
Microsemi APA600-BG456	Microsemi Analog Mixed Signal Group APA600-BG456	Microsemi Analog Mixed Signal Group [MIL] APA600-BG456
Microsemi Consumer Medical Product Group APA600-BG456	Microsemi HI-REL [MIL] APA600-BG456	Microsemi Power Management Group APA600-BG456
Microsemi Power Products Group APA600-BG456	Microsemi SoC APA600-BG456	Microsemi Commercial Components Group APA600-BG456
Microsemi Corporation APA600-BG456	Microsemi Solutions Sdn Bhd. APA600-BG456	

Related Products

 APA503-00-008 Manufacturers: Astec America (Artesyn Embedded Technologies) Description: STUD MTG SOLDER FOR HEATSINK LP In stock: Out stock RFQ	 APA600-BGG456M Manufacturers: Microsemi Description: IC FPGA 356 I/O 456BGA In stock: Out stock RFQ
 APA503-00-001 Manufacturers: Astec America (Artesyn Embedded Technologies) Description: STUD MTG TAPPED FOR HEATSINK In stock: Out stock RFQ	 APA503-00-007 Manufacturers: Astec America (Artesyn Embedded Technologies) Description: STUD MTG TAPPED FOR HEATSINK LP In stock: Out stock RFQ
 APA600-BG456M Manufacturers: Microsemi Description: IC FPGA 356 I/O 456BGA In stock: Out stock RFQ	 APA502-80-001 Manufacturers: Astec America (Artesyn Embedded Technologies) Description: PAD THERMAL SIZE80 FOR AMPSS MOD In stock: Out stock RFQ
 APA600-BGG456 Manufacturers: Microsemi Description: IC FPGA 356 I/O 456BGA In stock: Out stock RFQ	 APA600-BGG456I Manufacturers: Microsemi Description: IC FPGA 356 I/O 456BGA In stock: Out stock RFQ
 APA600-CGS624B Manufacturers: Microsemi Description: IC FPGA 440 I/O 624CGA In stock: Out stock RFQ	 APA504-00-001 Manufacturers: Astec America (Artesyn Embedded Technologies) Description: SOCKET SPRING(20-CONTROL/15-PWR) In stock: Out stock RFQ
 APA600-BG456I Manufacturers: Microsemi Description: IC FPGA 356 I/O 456BGA In stock: Out stock RFQ	 APA503-00-002 Manufacturers: Astec America (Artesyn Embedded Technologies) Description: STUD MTG SOLDER FOR HEATSINK In stock: Out stock RFQ